### 1. Basic Specifications
Fill in the blanks and check the appropriate boxes.

<table>
<thead>
<tr>
<th>Microcomputer family</th>
<th>HD</th>
<th>Operating frequency/voltage (H8 only) *4</th>
<th>MHz</th>
<th>V</th>
</tr>
</thead>
<tbody>
<tr>
<td>Application*1</td>
<td>□ Consumer use</td>
<td>Functions*2</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>□ Commercial use (industry, manufacturing, etc...)</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**ROM code name**

- ROM code media: □ ROM Code Receipt System

**Package*3**

- DP - ( )
- FP - ( )
- TFP - ( )
- CP - ( )
- Other ( )

**Operating temperature*3**

- Standard specifications
- Wide temperature range specifications, I specifications (-40°C to +85°C)
- J specifications (-40°C to +85°C)
- Other special specifications ( )

**Special Specifications**

- (product Specification, mark Specification, etc.)

**Notes:**
1. Describe the type of equipment in which the chip will be used. (E.g., cassette recorder, VCR, air conditioner, etc.)
2. Describe the function which the chip will control. (E.g., automatic song selection, tuner, temperature control, etc.)
3. Note that certain products have undetermined packages and operating temperatures.
4. Describe the operating frequency and the voltage version. (E.g., 8MHz/2.7V, 16MHz/5V, 10MHz/5V or etc.)

### 2. Application Environment Checklist
This checklist serves only as a reference for reliable design of the chip, and is not intended for determining guaranteed characteristic values. Actual guaranteed values of products will be determined according to the information entered in table 1 above, Basic Specifications.

<table>
<thead>
<tr>
<th>Microcomputer ambient temperature</th>
<th>Average</th>
<th>C</th>
<th>Range</th>
<th>C to C</th>
</tr>
</thead>
<tbody>
<tr>
<td>Microcomputer ambient humidity</td>
<td>Average</td>
<td>%</td>
<td>Range</td>
<td>% to %</td>
</tr>
<tr>
<td>Power on duration</td>
<td>Average</td>
<td>Hours per day</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

- Target level reliability: □ 500 fit
- □ 1000 fit
- □ Other (fit)

- Acceptable quality level (AQL): □ 1.0%
- □ 0.65%
- □ 0.4%
- □ Other ( )

- Package mounting method
  - Mounting method: □ Lead dip
  - □ Vapor phase reflow
  - □ Infrared reflow
  - □ Air reflow
  - □ Wave solder
  - □ Solder iron
  - □ Other ( )

- Mounting conditions
  - Temperature C
  - Seconds ( )

**Remarks**

* For more information, contact your local Renesas sales representative, or consult the Mounting Manual.

### 3. Checksum
Enter the last 4 digits of the checksum value of the first to last address of the ROM-Data you will be supplying.

<table>
<thead>
<tr>
<th>Start Address (Hexadecimal)</th>
<th>End Address (Hexadecimal)</th>
<th>Checksum value</th>
<th>Date of order</th>
</tr>
</thead>
<tbody>
<tr>
<td>(e.g.) 0</td>
<td>1FFFF</td>
<td>ABCD</td>
<td></td>
</tr>
</tbody>
</table>

Customer

Department

Name